



# SD019-111-411

## Surface Mount Silicon Photodiode with Integrated Bandpass Filter

The SD019-111-411 is 0.18mm<sup>2</sup> PIN silicon photodiode ideal for high-speed response applications assembled in a compact water clear surface-mount package. The device is available on Tape and Reel and designed for automated SMT assembly.

### Applications

Industrial Sensing  
Light Management  
Handheld Devices

### Features

Small Footprint  
Low Capacitance  
High Speed

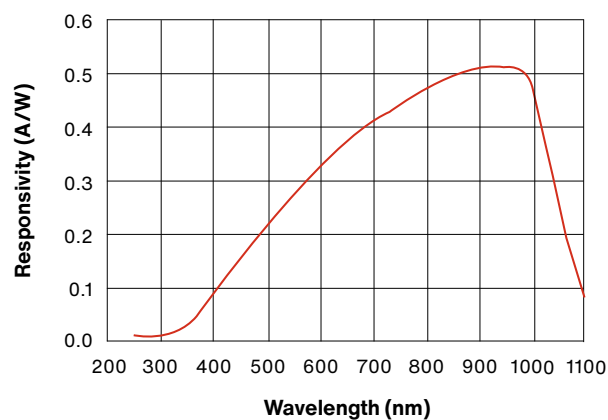
## Absolute Maximum Ratings

| Parameter             | Symbol    | Min | Max  | Unit |
|-----------------------|-----------|-----|------|------|
| Reverse Voltage       | $V_R$     | -   | 50   | V    |
| Operating Temperature | $T_{OP}$  | -40 | +100 | °C   |
| Storage Temperature   | $T_{STG}$ | -55 | +125 | °C   |
| Package               | 0805      |     |      |      |

## Typical Electro-Optical Specifications at $T_A=23\text{ °C}$

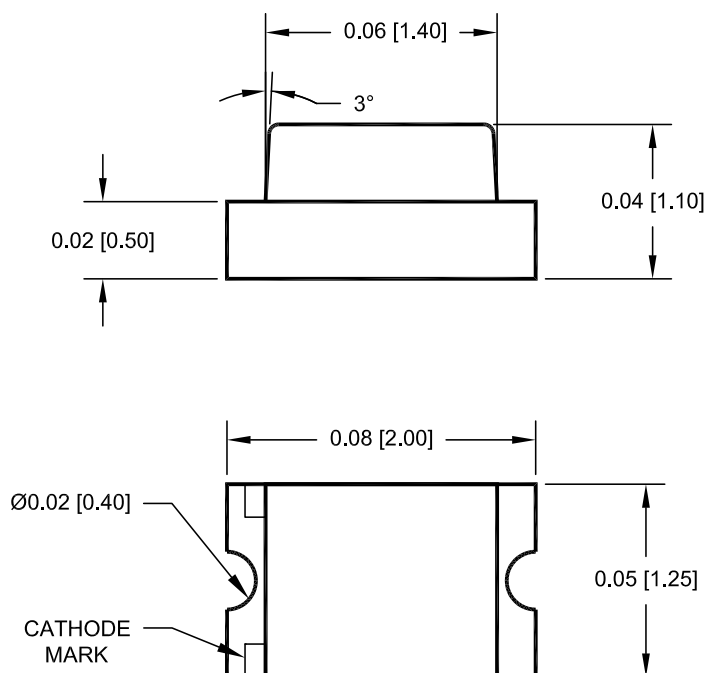
| Parameter             | Test Conditions                    | Symbol   | Min | Typ  | Max | Unit            |
|-----------------------|------------------------------------|----------|-----|------|-----|-----------------|
| Active Area           | -                                  | A.A.     | -   | 0.18 | -   | mm <sup>2</sup> |
| Capacitance           | $V_R = 5V$ ; $f = 1000\text{ kHz}$ | $C_J$    | -   | 6.0  | -   | pF              |
| Dark Current          | $V_R = 10V$                        | $I_D$    | -   | -    | 0.5 | nA              |
| Shunt Resistance      | $V_R = 10mV$                       | $R_{SH}$ | -   | 2.0  | -   | GΩ              |
| Forward Voltage       | $I_f = 10\text{ mA}$               | $V_F$    | 0.5 | 0.8  | 1.3 | V               |
| Light Current (2856K) | $V_R = 5V$ ; $\lambda = 1000nm$    | $I_L$    | -   | 3.2  | -   | μA              |

## Spectral Response

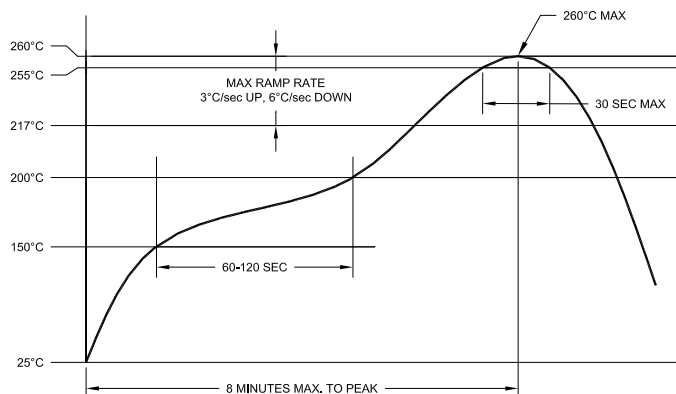


## Mechanical Specifications

Units are in inches (mm)



## Reflow Profile



## Soldering

| Recommendation             |             |                         |
|----------------------------|-------------|-------------------------|
| Wave                       | Not Advised | -                       |
| IR Oven Reflow             | Allowed     | See Reflow Profile      |
| Forced Convection Reflow   | Recommended | See Reflow Profile      |
| Convection Reflow          | Recommended | See Reflow Profile      |
| Vapor Phase Reflow         | Recommended | See Reflow Profile      |
| Manual                     | Allowed     | 260°C for 3 seconds max |
| Moisture Sensitivity Level | 3           | J-STD-033               |

## Care and handling instructions

Your optoelectronic components are packaged and shipped in opaque, padded containers to avoid ambient light exposure and damage due to shock from dropping or jarring.

Care must be taken to avoid exposure to high ambient light levels, particularly from tungsten sources or sunlight.

- These components can be rendered inoperable if dropped or sharply jarred. The wire bonds are delicate and can become separated from the bonding pads when the component is dropped or otherwise receives a sharp physical blow.
- Most windows on photodiodes are either silicon or quartz. They should be cleaned with isopropyl alcohol and a soft (optical grade) pad.
- Photodiode exposure to extreme high or low storage temperatures can affect the subsequent performance. Maintain a non-condensing environment for optimum performance and lifetime.
- All devices are considered ESD sensitive. The photodiodes are shipped in ESD protective packaging. When unpacking and using these products, anti-ESD precautions should be observed.
- Photodiode packages and/or operation may be impaired if exposed to CHLOROETHENE, THINNER, ACETONE, TRICHLOROETHYLENE or any harsh chemicals.
- Optoelectronic components in plastic packages should be given special care. Clear plastic packages are more sensitive to environmental stress than those of black plastic. Storing devices in high humidity can present problems when soldering. Since the rapid heating during soldering stresses the wire bonds and can cause wire to bonding pad separation, it is recommended that devices in plastic packages to be baked for 24 hours at 85°C.
- The leads on the photodiode **SHOULD NOT BE FORMED**. If your application requires lead spacing modification, please contact Advanced Photonix Applications group at [Techsupport@advancedphotonix.com](mailto:Techsupport@advancedphotonix.com) before forming a product's leads. Product warranties could be voided.
- Most devices are provided with wire or pin leads for installation in circuit boards or sockets. Observe the soldering temperatures and conditions specified below:
  - Soldering Iron: Soldering 30 W or less
  - Temperature at tip of iron 300°C or lower.
  - Dip Soldering: Bath Temperature: 260±5°C.
  - Immersion Time: within 5 Sec.
  - Soldering Time: within 3 Sec.
  - Vapor Phase Soldering, Reflow Soldering: **DO NOT USE**

## Legal Disclaimer

Information in this data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice.



Most of our standard catalog products are RoHS Compliant. Please contact us for details.

